

FIG. 2

FIG 3A

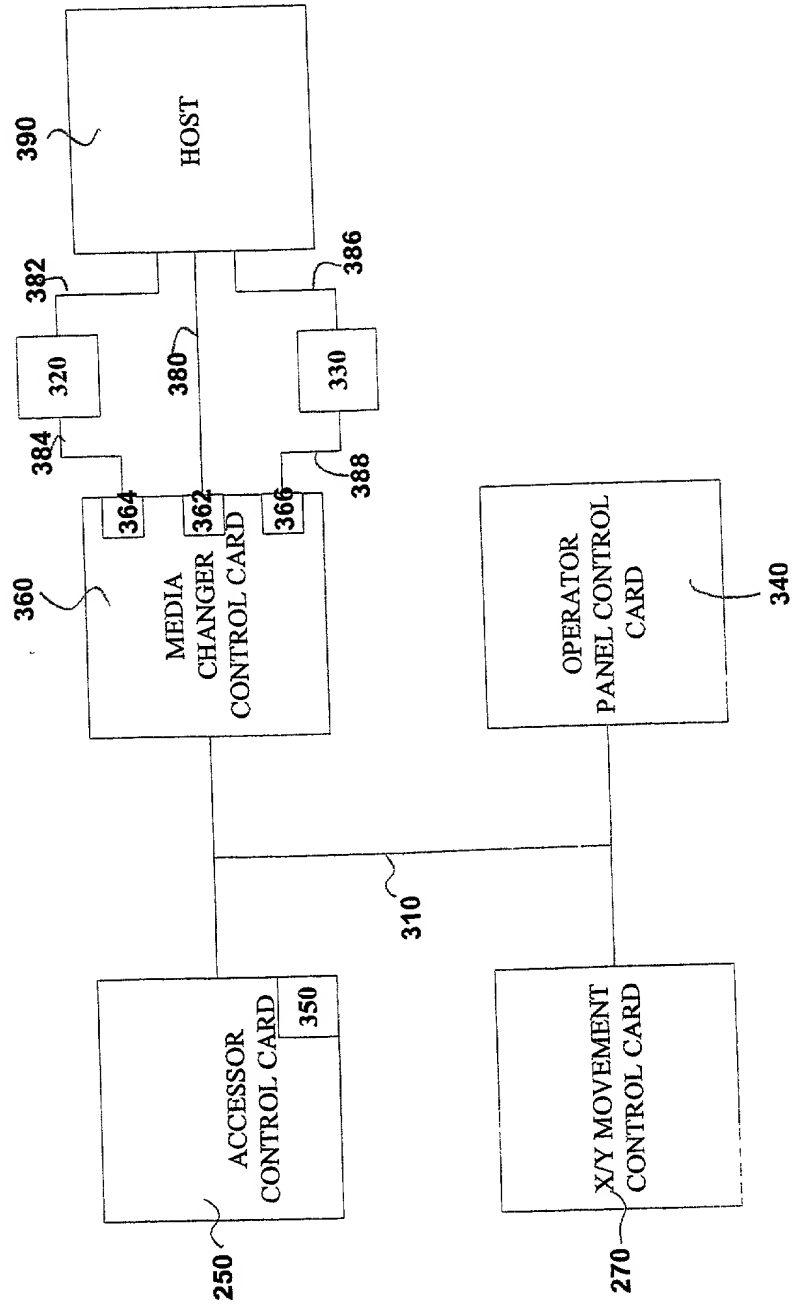


FIG. 3B

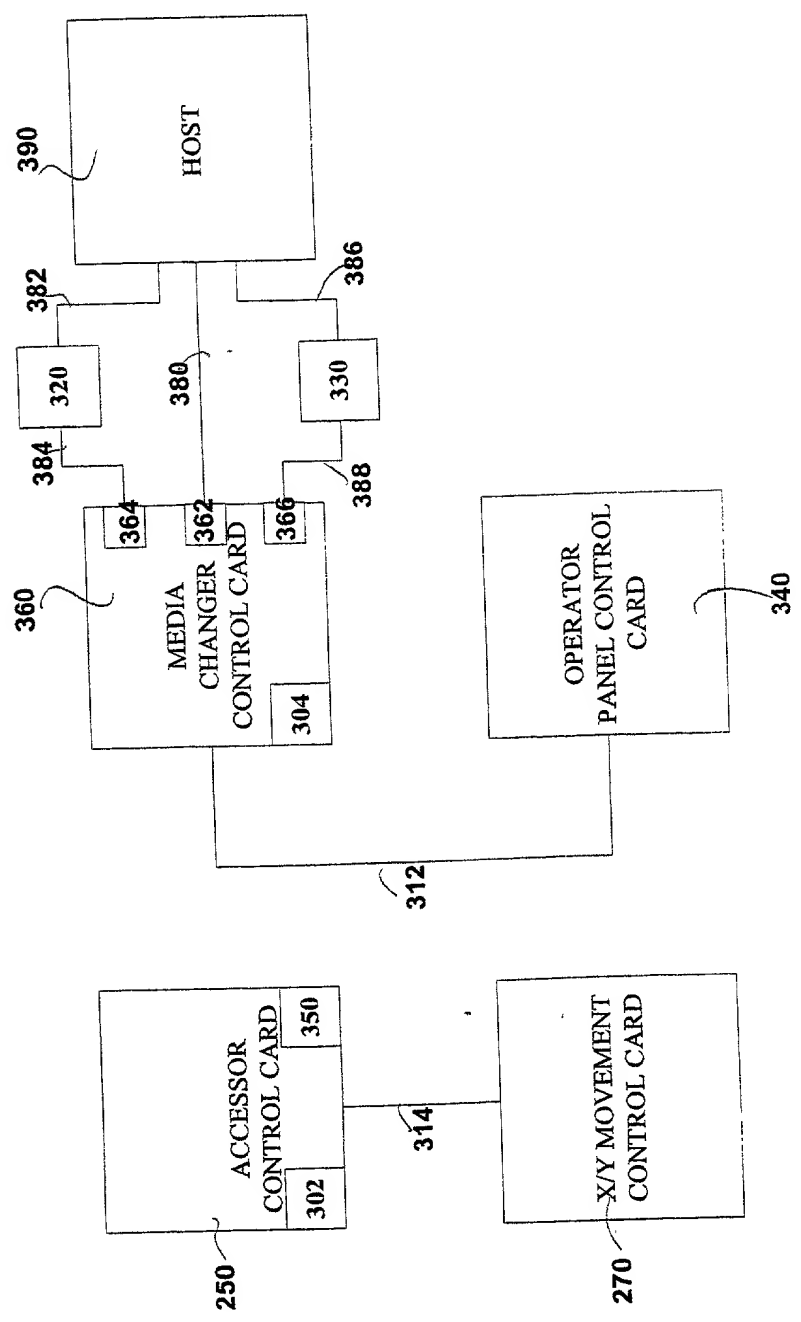


FIG. 3C

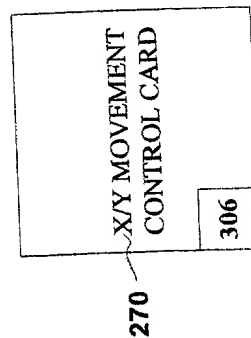
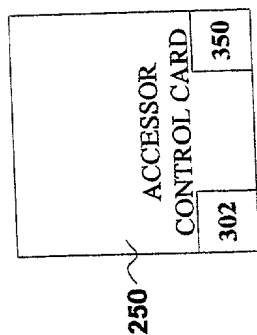
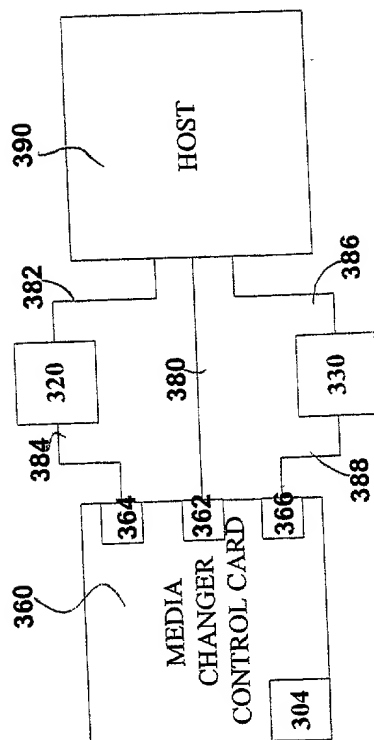


FIG. 4

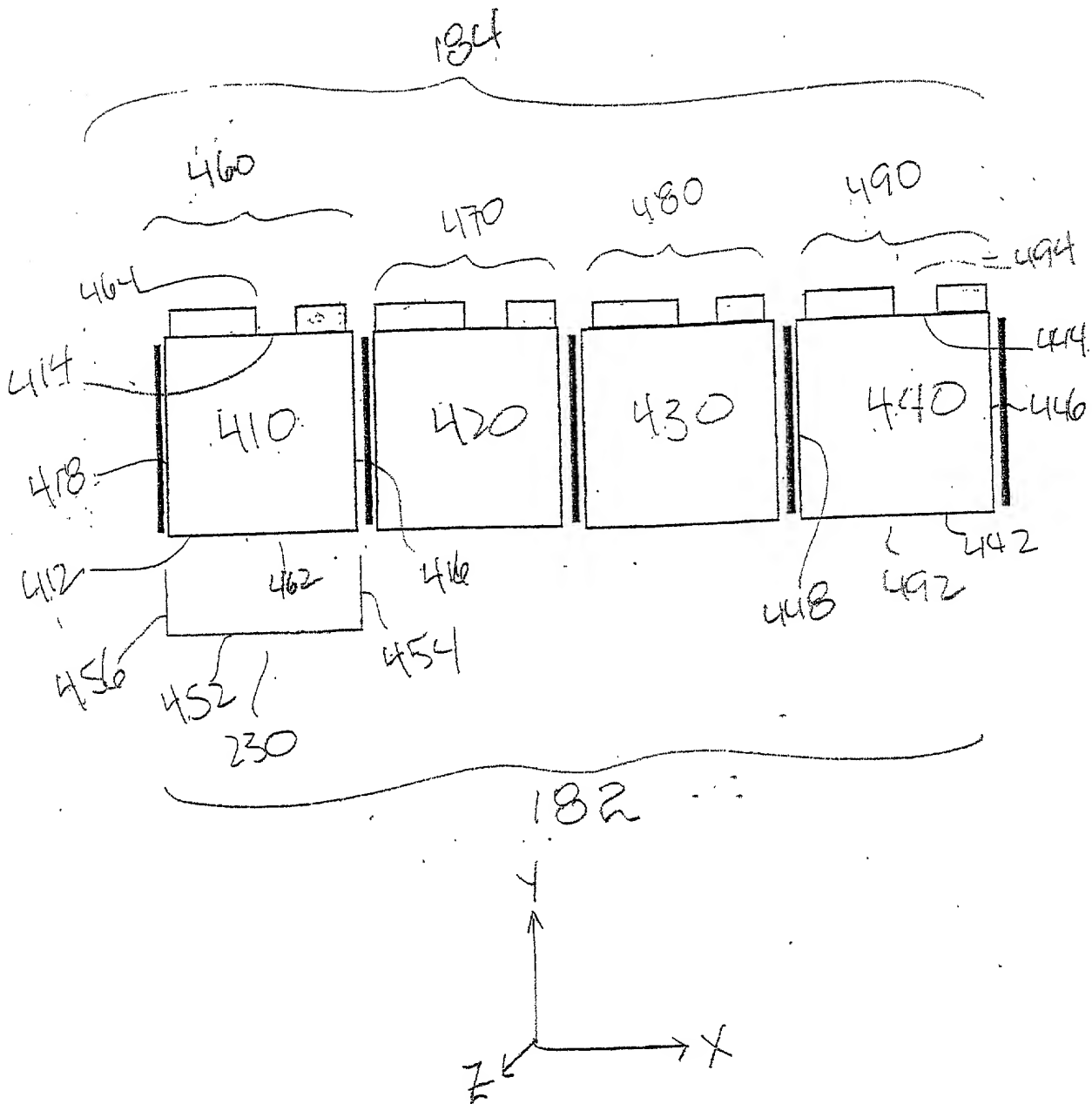
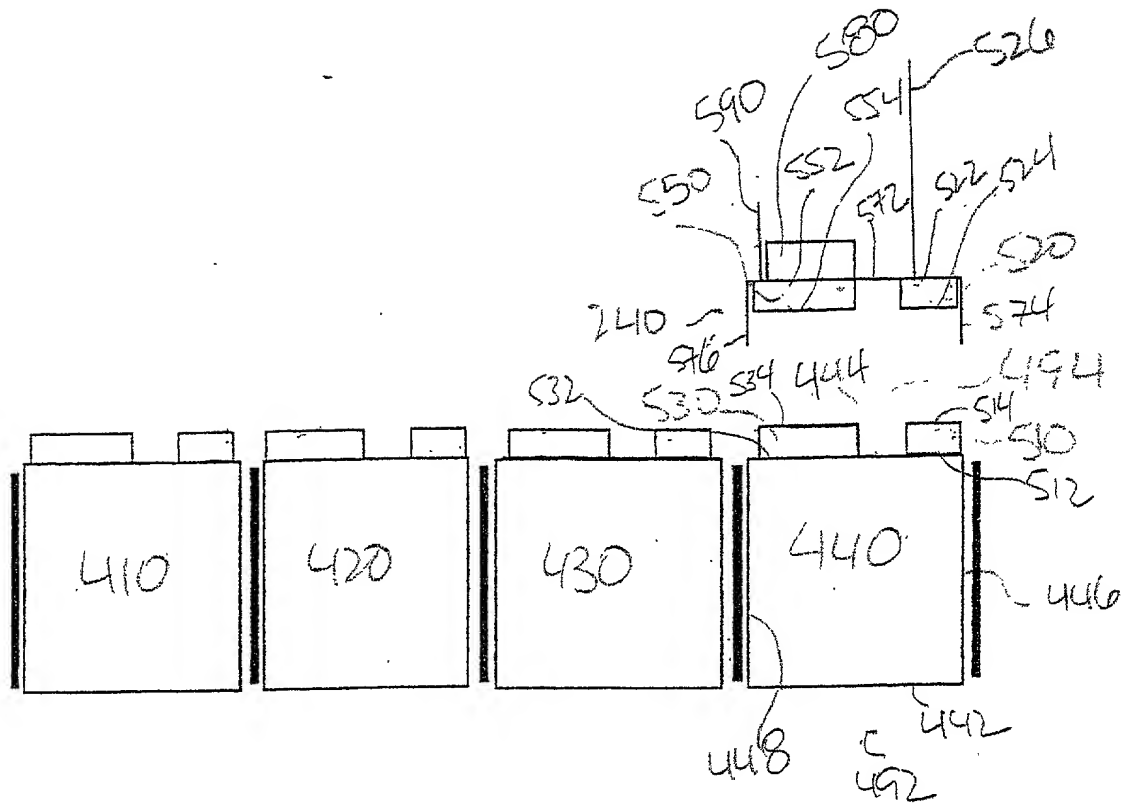
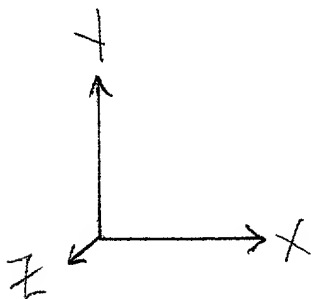


FIG. 5

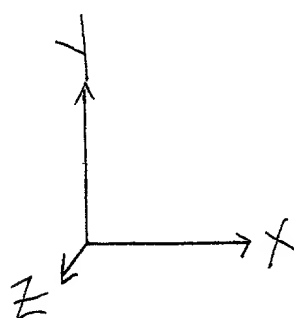


Hand-drawn schematic diagram of a device 320. The device consists of a top horizontal bar with vertical lines, a middle row of rectangular blocks, and a bottom row of rectangular blocks. A large square block labeled 410 is positioned below the middle row. Various components are labeled with handwritten numbers: 604, 650, 630, 382, 610, 640, 620, 670, 602, 660, and 670.





A hand-drawn schematic diagram of a semiconductor device structure. The diagram shows a cross-section of a substrate with several layers and features. The substrate is labeled 702. On top of the substrate, there are three rectangular regions labeled 710, 720, and 740. A layer labeled 730 is shown on the left side of the substrate. A layer labeled 540 is shown on top of the 710 region. A layer labeled 580 is shown on top of the 720 region. A layer labeled 520 is shown on top of the 740 region. A layer labeled 240 is shown on top of the 720 region. A layer labeled 590 is shown on top of the 540 region. A layer labeled 380 is shown on the left side of the substrate. A layer labeled 330 is shown on the right side of the substrate. A layer labeled 704 is shown on the right side of the substrate.



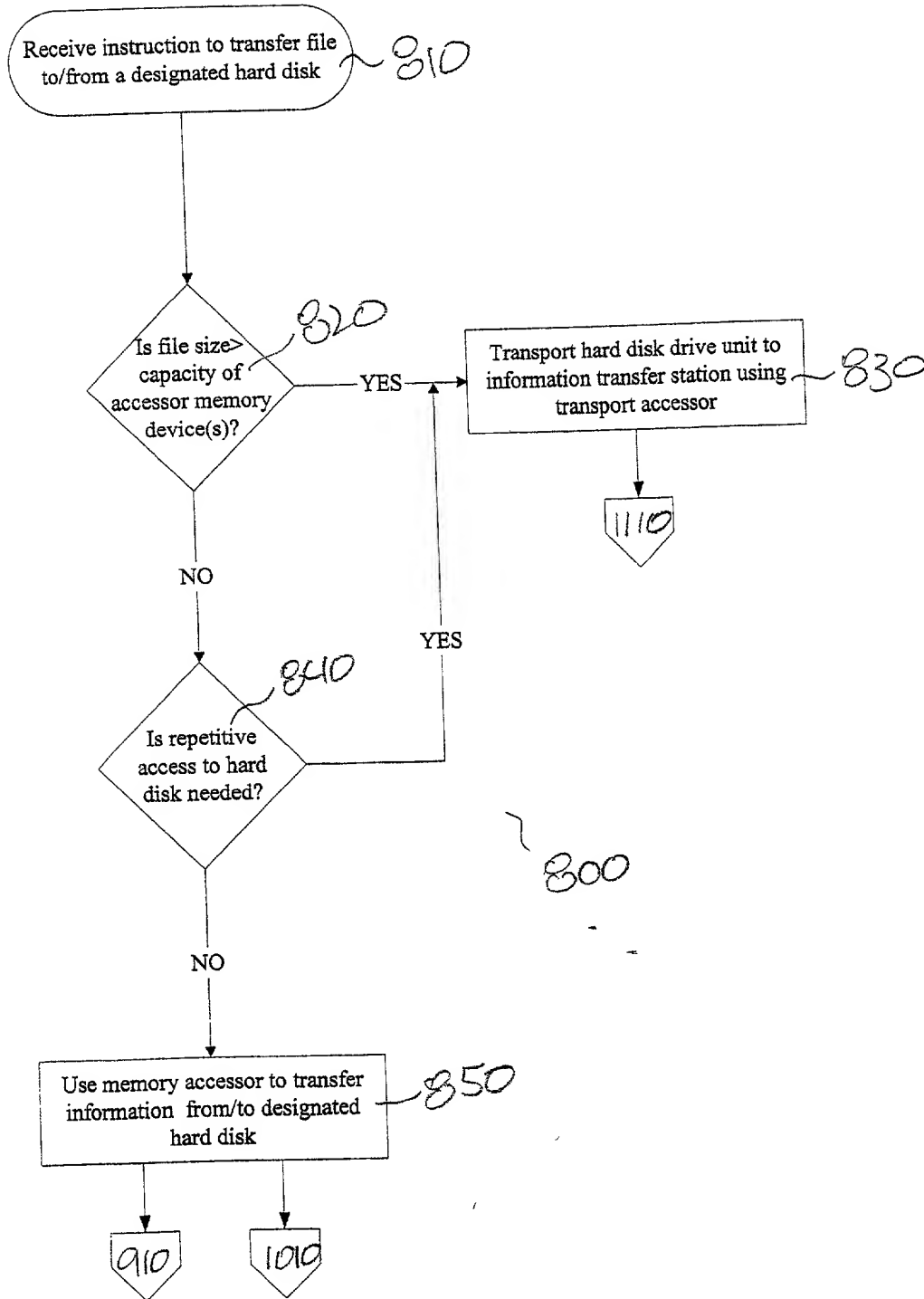


FIG. 8

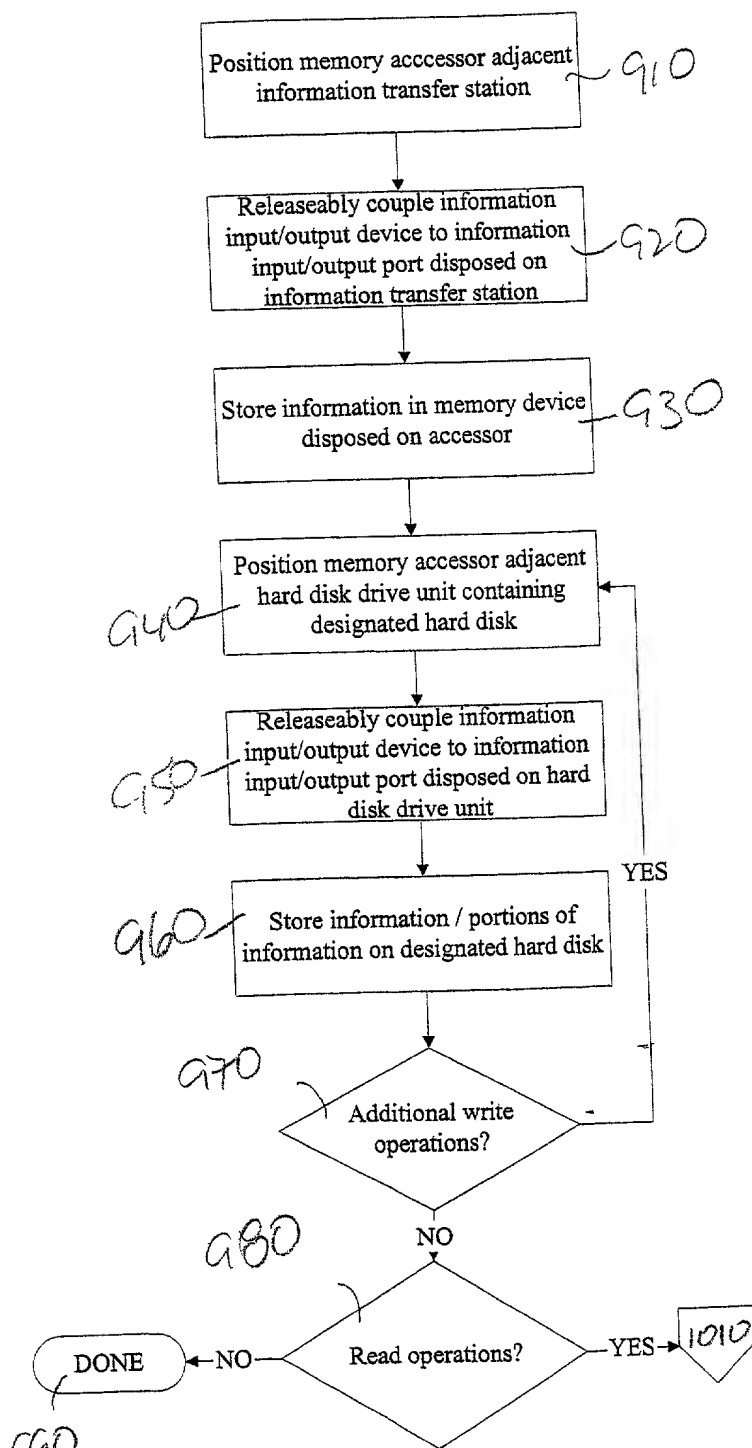


FIG. 9

